

## 100V N-Channel MOSFET

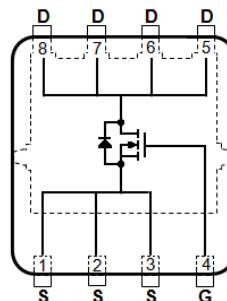
### Features

- 100% EAS Guaranteed
- Low RDS(ON)
- Low Gate Charge
- RoHs and Halogen-Free Compliant
- AEC-Q101 qualified (Automotive grade with suffix "Q".)
- Exsemi technology

### Product Summary

$V_{(BR)DSS}$	$R_{DS(on)}$	$I_D$
100V	8mΩ	48A

**DFN5060-8L**



### Description

The EP0048 is the high cell density trenched N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the Synchronous Rectification for AC/DC Quick Charger.

### Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	100	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D@T_c=25^\circ C$	Continuous Drain Current <sup>1</sup>	48	A
$I_D@T_c=70^\circ C$	Continuous Drain Current <sup>1</sup>	38	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	144	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	61	mJ
$I_{AS}$	Avalanche Current	35	A
$P_D@T_c=25^\circ C$	Total Power Dissipation <sup>4</sup>	108	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	---	55	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	4.0	°C/W

### Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	100	---	---	V
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=10\text{V}$ , $I_D=13.5\text{A}$	---	6.6	8	$\text{m}\Omega$
	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=4.5\text{V}$ , $I_D=11.5\text{A}$	---	8.7	10.5	
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D=250\mu\text{A}$	1.2	---	2.3	V
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=80\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\text{uA}$
		$V_{\text{DS}}=80\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=55^\circ\text{C}$	---	---	5	
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	$\text{nA}$
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=5\text{V}$ , $I_D=20\text{A}$	---	85	---	S
$Q_g$	Total Gate Charge (10V)	$V_{\text{DS}}=50\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $I_D=13.5\text{A}$	---	45	---	$\text{nC}$
$Q_g$	Total Gate Charge (4.5V)		---	19.3	---	
$Q_{\text{gs}}$	Gate-Source Charge		---	9.5	---	
$Q_{\text{gd}}$	Gate-Drain Charge		---	4.8	---	
$T_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DD}}=50\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_G=3\Omega$ , $I_D=13.5\text{A}$	---	10	---	$\text{ns}$
$T_r$	Rise Time		---	6.5	---	
$T_{\text{d(off)}}$	Turn-Off Delay Time		---	45	---	
$T_f$	Fall Time		---	7.5	---	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=50\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	3320	---	$\text{pF}$
$C_{\text{oss}}$	Output Capacitance		---	605	---	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	20	---	

### Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current <sup>1,5,6</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	48	A
$V_{\text{sp}}$	Diode Forward Voltage <sup>2</sup>	$V_{\text{GS}}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1.1	V
$t_{\text{rr}}$	Reverse Recovery Time	$I_F=13.5\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$ , $T_J=25^\circ\text{C}$	---	33	---	nS
$Q_{\text{rr}}$	Reverse Recovery Charge		---	150	---	nC

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}=25\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $L=0.3\text{mH}$ , $I_{\text{AS}}=35\text{A}$
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5.The data is theoretically the same as  $I_D$  and  $I_{\text{DM}}$  , in real applications , should be limited by total power dissipation.

## Typical Characteristics

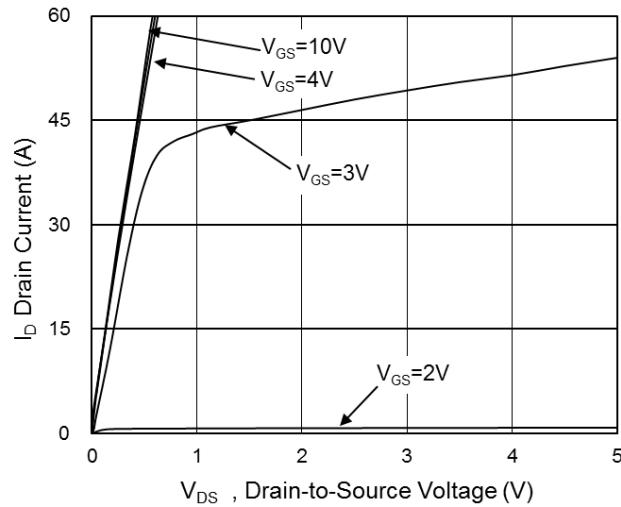


Fig.1 Typical Output Characteristics

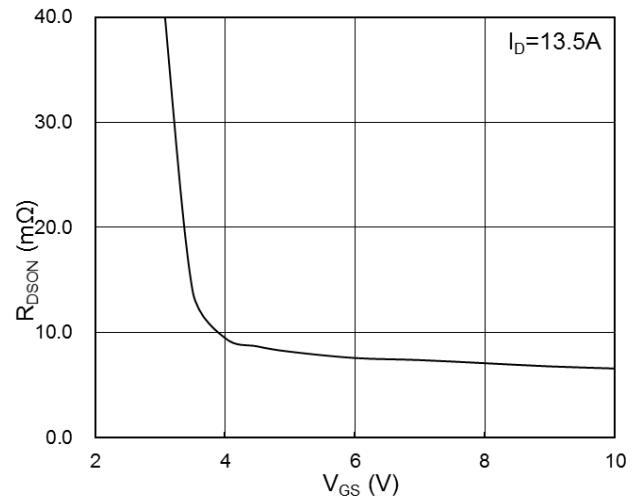


Fig.2 On-Resistance vs G-S Voltage

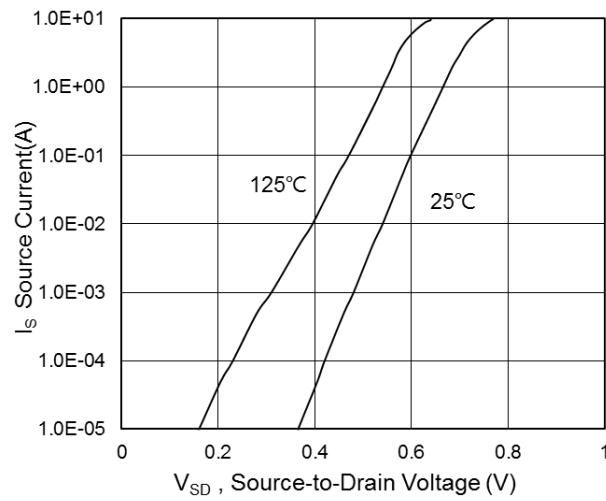


Fig.3 Source-Drain Forward Characteristics

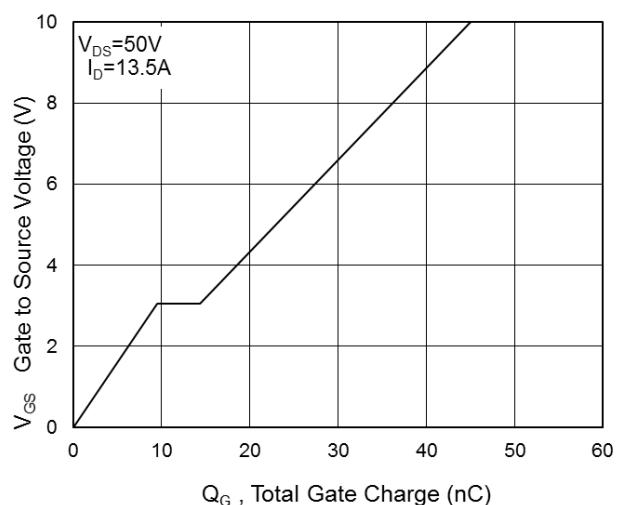


Fig.4 Gate-Charge Characteristics

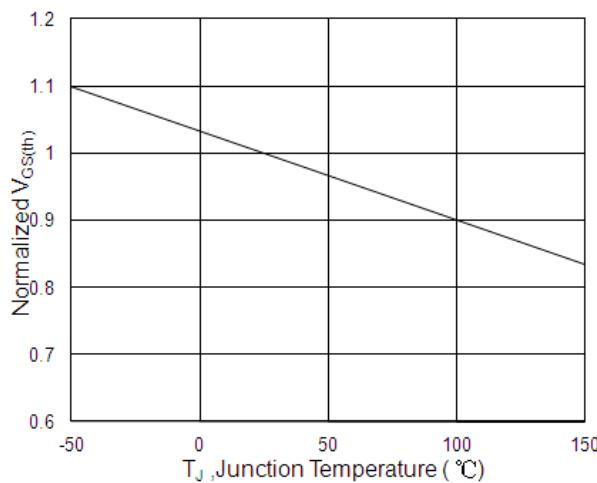


Fig.5 Normalized  $V_{GS(th)}$  vs  $T_J$

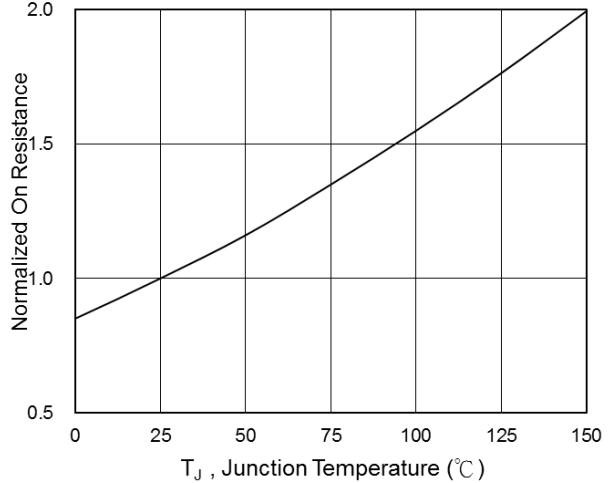


Fig.6 Normalized  $R_{DS(on)}$  vs  $T_J$

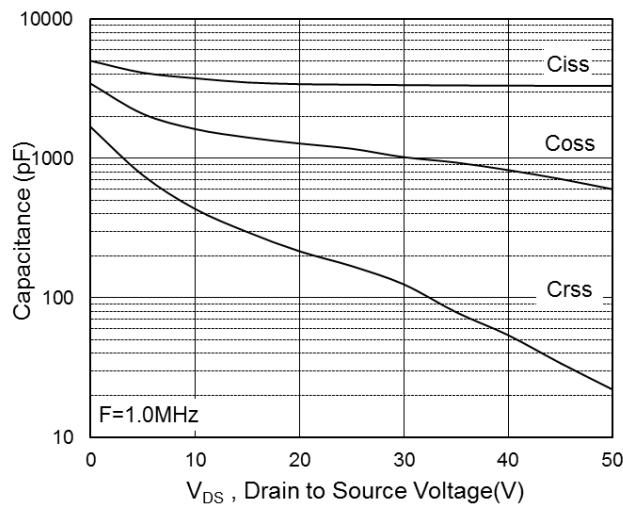


Fig.7 Capacitance

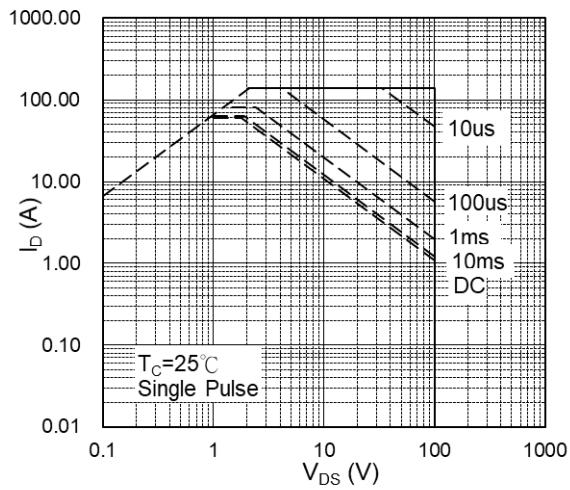


Fig.8 Safe Operating Area

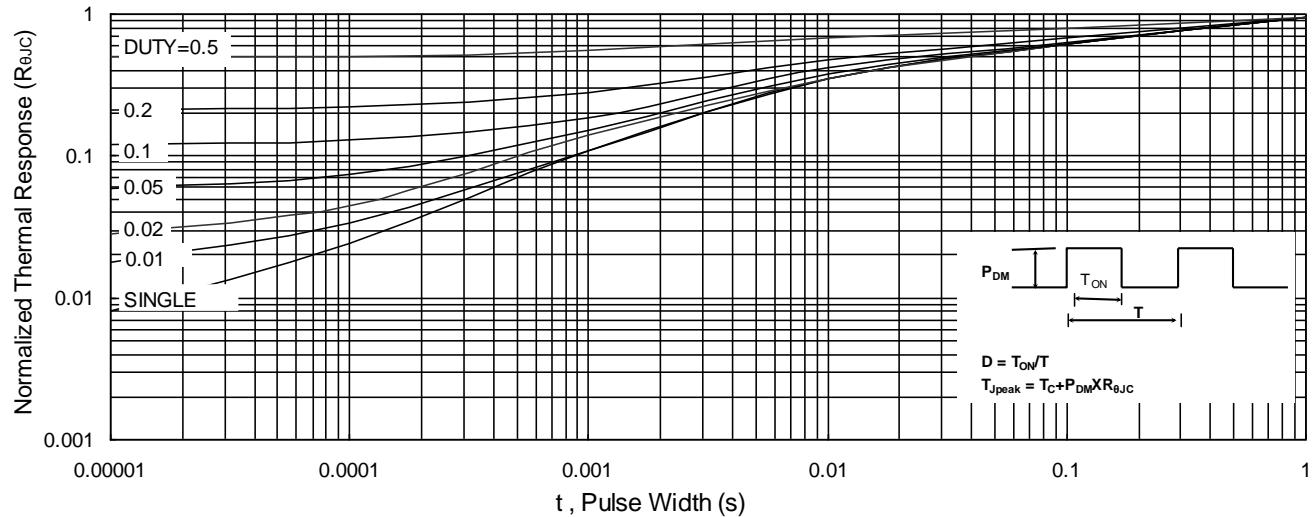


Fig.9 Normalized Maximum Transient Thermal Impedance

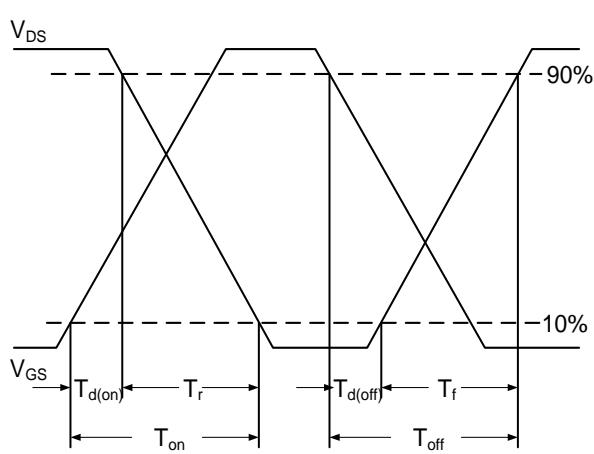


Fig.10 Switching Time Waveform

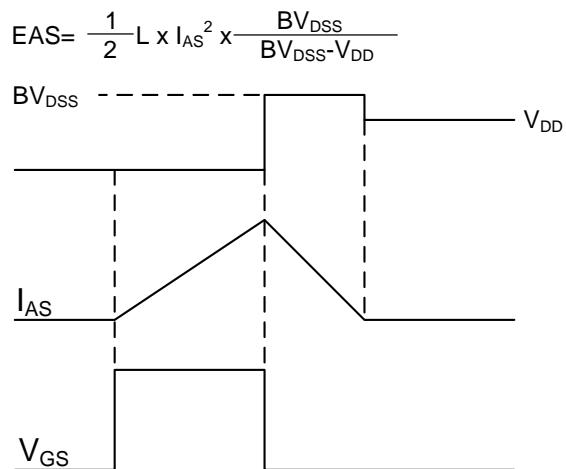
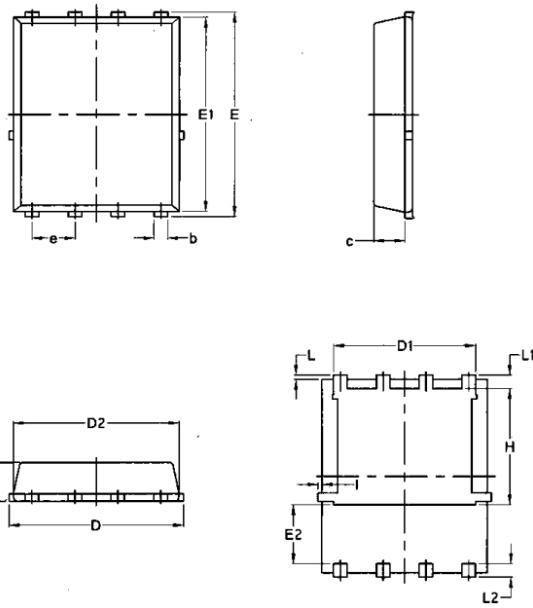


Fig.11 Unclamped Inductive Switching Waveform

## Package Outline Dimensions



Symbol	Common			
	mm		Inch	
	Min	Max	Min	Max
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.970	0.0324	0.082
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	/	0.0630	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	/	0.18	/	0.0070